

# THERMAL CONDUCTIVE ENCAPSULANT WITH PRIMERLESS ADHESION

If you are in search for an thermally conductive encapsulant which is easy to apply by low viscosity and you desire a primerless adhesion to many substrates our ELASTOSIL® RT 747 TC is the product of choice.

## Product Description

ELASTOSIL® RT 747 TC is a one component, low viscous, self-levelling and self-adhesive addition-curing one-component encapsulant that cures at elevated temperature to a thermally conductive silicone rubber with an heat conductivity of 1,4 W/mK.

## Features of ELASTOSIL® RT 747 TC

- One-component
- Thermally conductive
- Low viscosity for fast pouring / dispensing applications
- Self-levelling
- Good electrical insulation properties

## Applications

For heat ablation in potting applications in electronic devices such as

- Automotive electronics
- Coil potting
- Electric drives
- Various kinds of electronics control units

## Product Properties of ELASTOSIL® RT 747 TC

Viscosity at 23°C	D = 10 1/ sec	8.000
	D = 0,5 1/sec	45.000
Appearance		white
Density at 23°C	[g/cm³]	2.45
Thermal conductivity	[W/mK]	1.3
Hardness Shore A	[KME]	70
Tensile strength	[N/mm²]	2
Elongation at break	[%]	50
Tear resistance	[N/mm]	5.4
CTE (Thermal Expansion)	[10-6 m/mK]	120
Adhesion to PBT ULTRADUR BG 4300	[N/mm²]	0.8
Adhesion to GF 30		cohesive
Adhesion to FR4-PCB		cohesive



## Curing Proposal

Curing Temperature	Curing time (thickness 10mm)
130°C	30 min
150°C	15 min

## Your PLUS

ELASTOSIL® RT 747 TC shows outstanding rheologic and levelling properties with low viscosity and good primerless adhesion.

This feature allows also a convenient material handling and easiness of homogenization (in hobbock).

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**ELASTOSIL®**